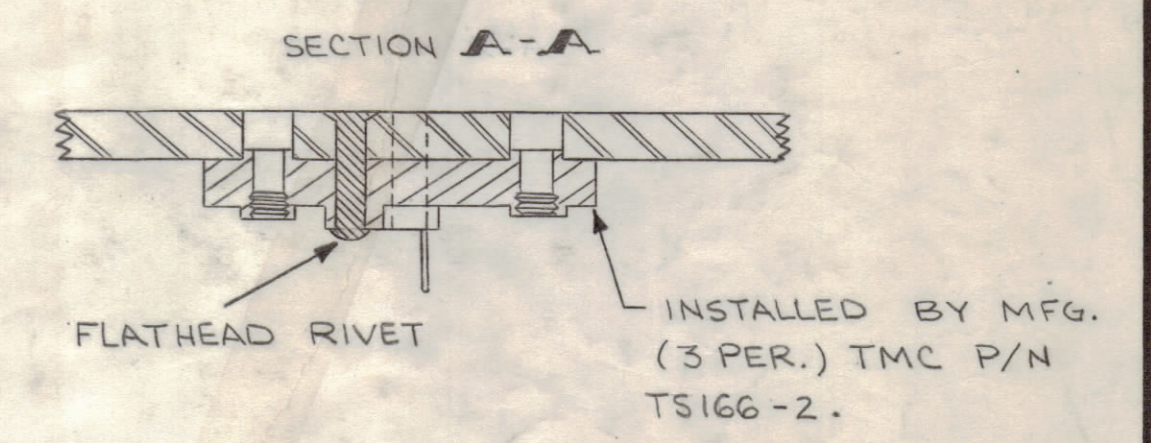
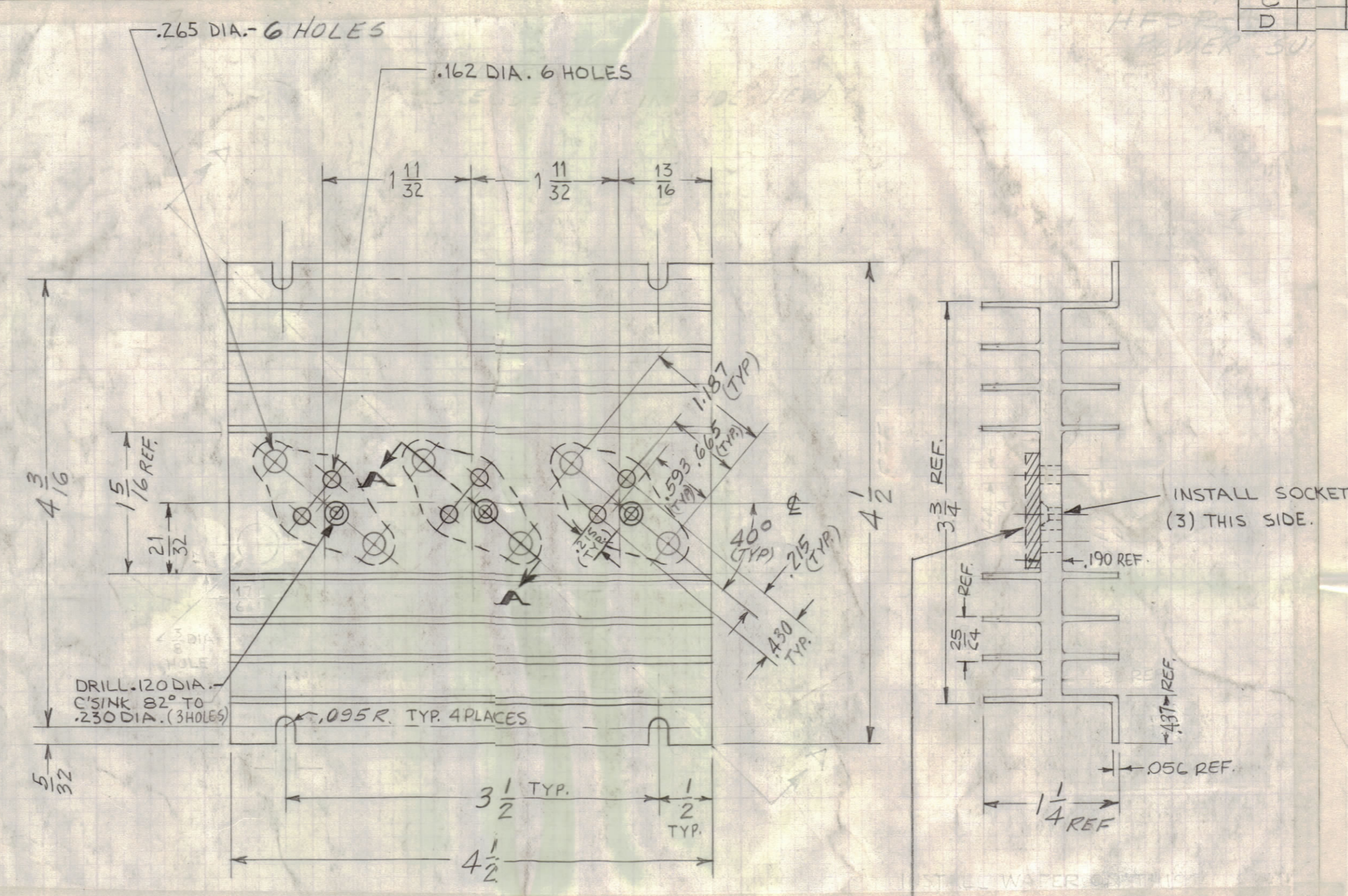


TMC P/N	*WAFER	USED ON
HD106	NONE	MMX()
HD106-2	3REQ'D	HFSR-4

REVISIONS						
SYM	ZONE	DESCRIPTION	DATE	E.M.N.NO.	DRAFT	CHKD
X		EXPERIMENTAL RELEASE	1/31/66	X	RME	
X1		CHG'D 13/8 DIMS TO 1-11/32 & 7/8 TO 13/16 & 7/32 DIA TO .265. CHG'D .111 DIA. C'BORE .144 TO X 1/16 DP. TO .162 DIA TOP SIDE. ADDED 3/8 HOLE	12-8-66	X1	RME	
X2		ADDED C'SUNK HOLE & SECTION VIEW A-A.	2-16-67	X2	RME	
Ø		ORIGINAL RELEASE FOR PRODUCTION	6-26-67	Ø	RG	
A		MOD. HFSR-4 DELE. MOD. MMX.() ADDED	10/29/67	C.C.		
B		HD106-2 & WAFER NOTES ADDED	1-24-68	18740		
C		DIM CHG 4 1/2 WAS 4 1/2 REF.	6.10.68	19481	GE	
D		DELETE 3/8 HOLE	1/5/70	19694	KD	



- * NOTES:
1. WAFER MATERIAL-BERYLLIUM OXIDE, TO BE INSTALLED BY MFG.
 2. SURFACE FOR BERYLLIUM OXIDE MUST BE FLAT.
 3. SOCKET AND WAFER TO ACCEPT TO-3 TYPE SEMI CONDUCTOR.

UNLESS OTHERWISE SPECIFIED:

1. USE MATERIAL THICKNESS FOR MAXIMUM RADIUS ON ALL BENDS
2. ALL ANGULAR BENDS 90 DEGREES
3. REMOVE ALL BURRS AND SHARP EDGES
4. MOUNT INSERTS AFTER FINISHING

HD 106-2	1	HFSR-4	
HD 106-1	1	MMX-()	BMA 173
HD 106-1	1	MMX-1	BMA 173
HD 106-1	1	VOX-7	BMA 104
HD 106-1	QTY. REQ.	MODEL USED ON	ASSY. NO.

MAXIMUM ALLOWABLE TOLERANCES HAVE BEEN DETERMINED AND ANY DEVIATIONS WILL BE CAUSE FOR REJECTION.

QTY REQ	ITEM	PART NO.	DESCRIPTION	SYMBOL
			BILL OF MATERIAL REF. SK 3213 HD1	
			THE TECHNICAL MATERIEL CORP. MAMARONECK, NEW YORK	
			HEAT SINK, POWER SUPPLY	
			CODE 82679	SIZE C
			DWG. NO. HD 106	ISSUE D
			SCALE	SHEET 1 OF 1

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON FRACTIONS DECIMALS ANGLES ±1/64 ±.005 ±1/2°

MATERIAL ALUMINUM EXTRUSION 6063-T6

FINISH SIZE BLACK ANODIZE

FINAL APPROVAL	DATE 6/26/67
MECH. DES. SAC	DATE 6/23/67
ELECT. DES.	DATE
CHECKED	DATE 6-22-67
DRAWN RME	DATE 10/31/66
APPROVED FOR BUSHIPS	DATE 6/26/67
(S401-408 (1311))	
S401-105 (8043 163)(WAFER ONLY)	